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Renesas Technology Corp.
Customer Support Dept.
April 1, 2003

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Keep safety first in your circuit designs!

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Remember to give due consideration to safety when making your circuit designs, with appropriate measures such as (i) placement of substitutive, auxiliary circuits, (ii) use of nonflammable material or (iii) prevention against any malfunction or mishap.

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HD74HC107

Dual J-K Flip-Flops (with Clear)



ADE-205-432 (Z)

1st. Edition

Sep. 2000

Description

This flip-flop is edge sensitive to the clock input and change state on the negative going transition of the clock pulse. Each one has independent J, K, clock, and clear inputs and Q and \bar{Q} outputs. Clear is independent of the clock and accomplished by a low level on the input.

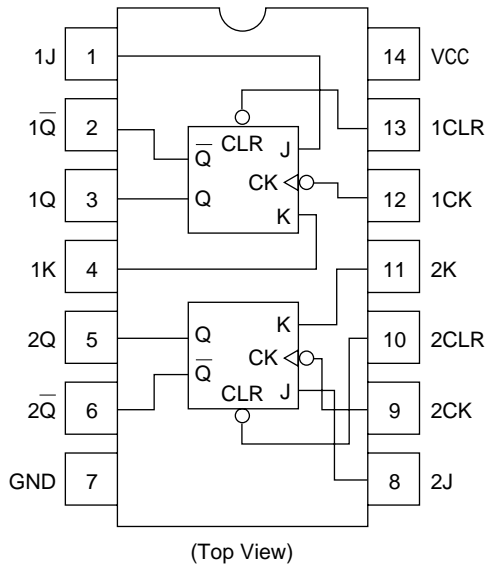
Features

- High Speed Operation: t_{pd} (Clock to Q) = 19 ns typ ($C_L = 50$ pF)
- High Output Current: Fanout of 10 LSTTL Loads
- Wide Operating Voltage: $V_{CC} = 2$ to 6 V
- Low Input Current: 1 μ A max
- Low Quiescent Supply Current: I_{CC} (static) = 2 μ A max ($T_a = 25^\circ\text{C}$)

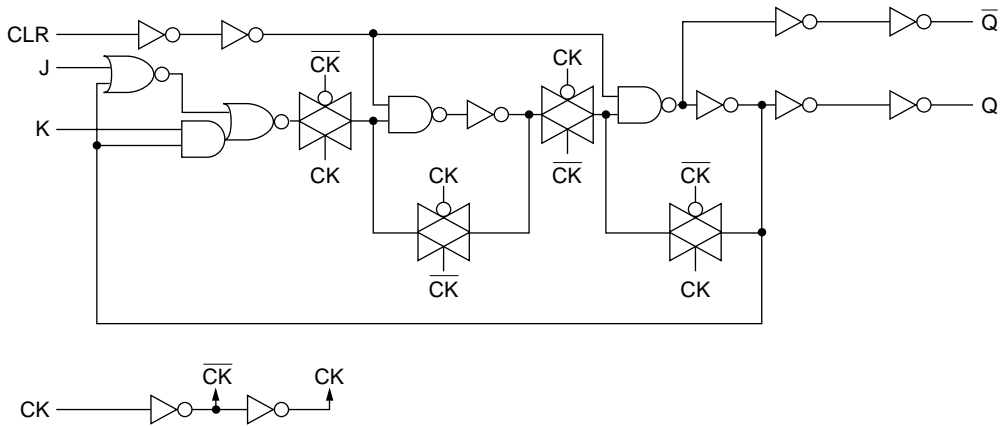
Function Table

Inputs				Output	
Clear	Clock	J	K	Q	\bar{Q}
L	X	X	X	L	H
H		L	L	No change	
H		L	H	L	H
H		H	L	H	L
H		H	H	Toggle	
H	L	X	X	No change	
H	H	X	X	No change	
H		X	X	No change	

Pin Arrangement



Block Diagram (1/2)



DC Characteristics

Item	Symbol	V _{CC} (V)	Ta = 25°C		Ta = -40 to +85°C		Unit	Test Conditions		
			Min	Typ	Max	Min			Max	
Input voltage	V _{IH}	2.0	1.5	—	—	1.5	—	V		
		4.5	3.15	—	—	3.15	—			
		6.0	4.2	—	—	4.2	—			
	V _{IL}	2.0	—	—	0.5	—	0.5	V		
		4.5	—	—	1.35	—	1.35			
		6.0	—	—	1.8	—	1.8			
Output voltage	V _{OH}	2.0	1.9	2.0	—	1.9	—	V	Vin = V _{IH} or V _{IL} I _{OH} = -20 μA	
		4.5	4.4	4.5	—	4.4	—			
		6.0	5.9	6.0	—	5.9	—			
		4.5	4.18	—	—	4.13	—			I _{OH} = -4 mA
		6.0	5.68	—	—	5.63	—			I _{OH} = -5.2 mA
	V _{OL}	2.0	—	0.0	0.1	—	0.1	V	Vin = V _{IH} or V _{IL} I _{OL} = 20 μA	
		4.5	—	0.0	0.1	—	0.1			
		6.0	—	0.0	0.1	—	0.1			
		4.5	—	—	0.26	—	0.33			I _{OL} = 4 mA
		6.0	—	—	0.26	—	0.33			I _{OL} = 5.2 mA
Input current	I _{in}	6.0	—	—	±0.1	—	±1.0	μA	Vin = V _{CC} or GND	
Quiescent supply current	I _{CC}	6.0	—	—	2.0	—	20	μA	Vin = V _{CC} or GND, I _{out} = 0 μA	

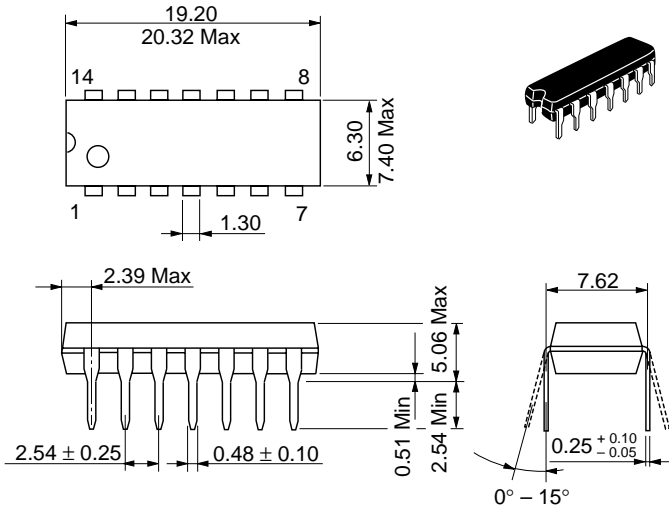
HD74HC107

AC Characteristics ($C_L = 50$ pF, Input $t_r = t_f = 6$ ns)

Item	Symbol	V_{CC} (V)	$T_a = 25^\circ\text{C}$		$T_a = -40$ to $+85^\circ\text{C}$		Unit	Test Conditions	
			Min	Typ	Max	Min			Max
Maximum clock frequency	f_{max}	2.0	—	—	6	—	5	MHz	
		4.5	—	—	30	—	24		
		6.0	—	—	35	—	28		
Propagation delay time	t_{PLH}	2.0	—	—	150	—	190	ns	Clock to Q or \bar{Q}
		4.5	—	19	30	—	38		
		6.0	—	—	26	—	33		
	t_{PHL}	2.0	—	—	140	—	175	ns	Clear to Q or \bar{Q}
		4.5	—	17	28	—	35		
		6.0	—	—	24	—	30		
Pulse width	t_w	2.0	80	—	—	100	—	ns	Clock, Clear
		4.5	16	7	—	20	—		
		6.0	14	—	—	17	—		
Setup time	t_{su}	2.0	100	—	—	125	—	ns	J or K to Clock
		4.5	20	3	—	25	—		
		6.0	17	—	—	21	—		
Hold time	t_h	2.0	5	—	—	5	—	ns	Clock to J or K
		4.5	5	-2	—	5	—		
		6.0	5	—	—	5	—		
Removal time	t_{rem}	2.0	100	—	—	125	—	ns	Clear to Clock
		4.5	20	0	—	25	—		
		6.0	17	—	—	21	—		
Output rise/fall time	t_{TLH}	2.0	—	—	75	—	95	ns	
		4.5	—	5	15	—	19		
	t_{THL}	6.0	—	—	13	—	16		
Input capacitance	C_{in}	—	—	5	10	—	10	pF	

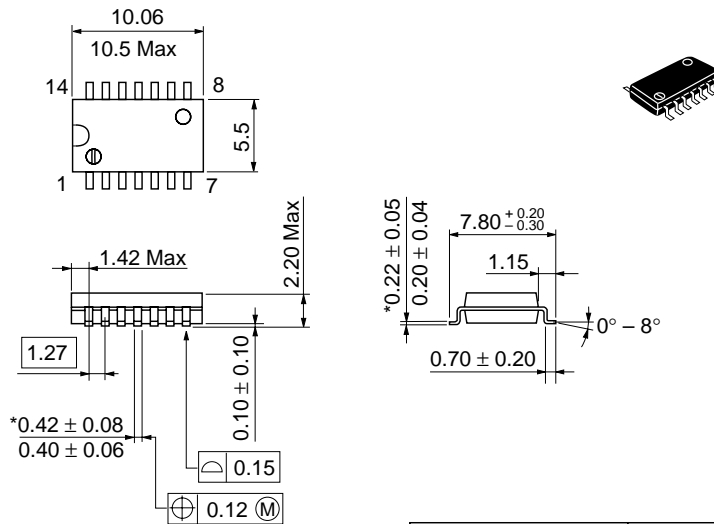
Package Dimensions

Unit: mm



Hitachi Code	DP-14
JEDEC	Conforms
EIAJ	Conforms
Mass (reference value)	0.97 g

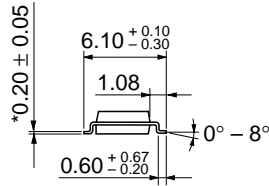
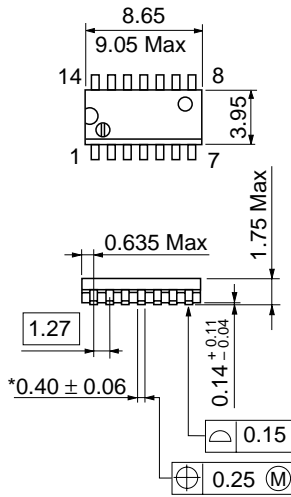
Unit: mm



*Dimension including the plating thickness
Base material dimension

Hitachi Code	FP-14DA
JEDEC	—
EIAJ	Conforms
Mass (reference value)	0.23 g

Unit: mm



*Pd plating

Hitachi Code	FP-14DN
JEDEC	Conforms
EIAJ	Conforms
Mass (reference value)	0.13 g

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